

IN THE CLAIMS:

Please cancel claims 1-8 without prejudice to or disclaimer of the subject matter recited therein.

Please add new claims 9-16 as follows:

LISTING OF CURRENT CLAIMS

Claims 1-8. (Canceled)

Claim 9. (New) A bonding pad structure for improving impedance matching, which is used in an electrical device having a plurality of electrically-connected layers for signal transmission and grounding, comprising:

5 at least two bonding pads including a first bonding pad and a second bonding pad, each of the at least two bonding pads having:

- a) at least two plugs; and
- b) at least two metal layers,

10 wherein, each of the at least two metal layers are electrically connected to and spaced apart by one of the at least two plugs, ends of at least two of the at least two metal layers of the first bonding pad are alternately spaced apart and overlapped with ends of at least two of the at least two metal layers of the second bonding pad.

Claim 10. (New) The bonding pad structure according to claim 9, wherein each of the at least two plugs and each of that least two metal layers are located in insulation layers of the electrical device.

Claim 11. (New) The bonding pad structure according to claim 9, wherein the electronic device is a printed circuit board.

Claim 12. (New) The bonding pad structure according to claim 9, wherein the electronic device is a chip.

Claim 13. (New) The bonding pad structure according to claim 12, wherein the chip includes six metal layers.

Claim 14. (New) The bonding pad structure according to claim 9, wherein the at least two bonding pads includes the first bonding pad, the second bonding pad, and a third bonding pad.

5 Claim 15. (New) The bonding pad structure according to claim 14, wherein each of the first bonding pad, the second bonding pad, and the third bonding pad have three plugs and three metal layers respectively, the first bonding pad has first, third, and fifth metal layers, the second bonding pad has second, fourth, and sixth metal layers, the third bonding pad has first, third, and fifth metal layers, the second metal layer is located above the first metal layer, the third metal layer is located above the second metal layer, the fourth metal layer is located above the third metal layer, the fifth metal layer is located above the fourth metal layer, and the sixth metal layer is located above the fifth metal layer.

Claim 16. (New) The bonding pad structure according to claim 14, wherein one end of the first, third, and fifth metal layers of the first bonding pad overlap a first end of the second, and fourth metal layers of the second bonding pad, and one end of the first, third, and fifth metal layers of the third bonding pad overlap a second end of the second, and fourth metal layers of the second bonding pad.